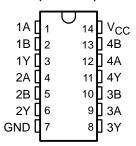
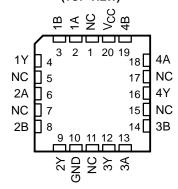
- Operating Voltage Range of 4.5 V to 5.5 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20-μA Max I<sub>CC</sub>

SN54HCT32...J OR W PACKAGE SN74HCT32...D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



- Typical t<sub>pd</sub> = 13 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible

# SN54HCT32...FK PACKAGE (TOP VIEW)



NC - No internal connection

#### description/ordering information

The 'HCT32 devices contain four independent 2-input OR gates. They perform the Boolean function  $Y = \overline{A} \bullet \overline{B}$  or Y = A + B in positive logic.

#### ORDERING INFORMATION

TA	PACKAGE <sup>†</sup>		PACKAGE <sup>†</sup> ORDERABLE PART NUMBER	
	PDIP – N	PDIP – N Tube		SN74HCT32N
	2010 B	Tube	SN74HCT32D	LIOTOO
	SOIC – D	Tape and reel	SN74HCT32DR	HCT32
-40°C to 85°C	SOP – NS Tape and ree		SN74HCT32NSR	HCT32
	SSOP - DB	Tape and reel	SN74HCT32DBR	HT32
	T000D DW	Tube	SN74HCT32PW	LITOS
	TSSOP – PW	Tape and reel	SN74HCT32PWR	HT32
	CDIP – J	Tube	SNJ54HCT32J	SNJ54HCT32J
–55°C to 125°C	CFP – W Tube		SNJ54HCT32W	SNJ54HCT32W
	LCCC – FK	Tube	SNJ54HCT32FK	SNJ54HCT32FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

## FUNCTION TABLE (each gate)

(**************************************									
INP	UTS	OUTPUT							
Α	В	Y							
Н	Χ	Н							
Χ	Н	Н							
L	L	L							



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (se	ee Note 1)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	c) (see Note 1)	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	····	±25 mA
Continuous current through V <sub>CC</sub> or GND		
Package thermal impedance, $\theta_{JA}$ (see Note 2):	D package	86°C/W
•	DB package	96°C/W
	N package	80°C/W
	NS package	76°C/W
	PW package	113°C/W
Storage temperature range, T <sub>stg</sub>		–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### recommended operating conditions (see Note 3)

			SI	SN54HCT32		SN74HCT32			LINUT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	\$ 5.5	4.5	5	5.5	V
VIH	High-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2	Š	7/	2			V
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V		75	0.8			0.8	V
٧ <sub>I</sub>	Input voltage		0	1	VCC	0		VCC	V
٧o	Output voltage		0	2	Vcc	0		Vcc	V
$\Delta t/\Delta v$	Input transition rise/fall time		000	) <sup>*</sup>	500			500	ns
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS		.,	Т	T <sub>A</sub> = 25°C			ICT32	SN74HCT32		
PARAMETER	TEST CO	NUTTIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
\/	\\.\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	$I_{OH} = -20  \mu A$	451/	4.4	4.499		4.4		4.4		\ <u>/</u>
Voн	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		V
\/-·	Mr. Marian Mar	$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1	.,
VOL	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 4 \text{ mA}$			0.17	0.26		0.4		0.33	V
lį	VI = VCC or 0		5.5 V		±0.1	±100	-	±1000		±1000	nA
ICC	$V_I = V_{CC}$ or 0,	IO = 0	5.5 V			2	(0)	40		20	μΑ
ΔI <sub>CC</sub> †	One input at 0.5 V Other inputs at 0 or		5.5 V		1.4	2.4	9000	3		2.9	mA
C <sub>i</sub>			4.5 V to 5.5 V		3	10	7	10		10	pF

<sup>†</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or VCC.

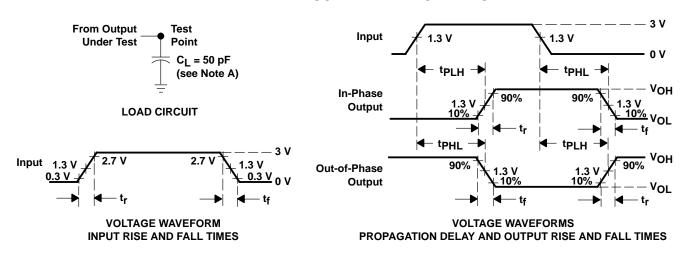
# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	то		FROM TO		T,	գ = 25°C	;	SN54HCT32	SN	74HCT32	
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN MA	х м	IN MAX	UNIT			
	A == D	Υ -	4.5 V		15	24	.63	5	30				
<sup>t</sup> pd	A or B		Y	Ť	5.5 V		13	22	0),619	2	27	ns	
		V	4.5 V		9	15	POET 2	2	19				
Ц		5.5	5.5 V		8	14	2	0	17	ns			

## operating characteristics, T<sub>A</sub> = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per gate	No load	20	pF

#### PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and test-fixture capacitance.
  - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f = 6 \ ns$ ,  $t_f = 6 \ ns$ .
  - C. The outputs are measured one at a time with one input transition per measurement.
  - D. tpLH and tpHL are the same as tpd.

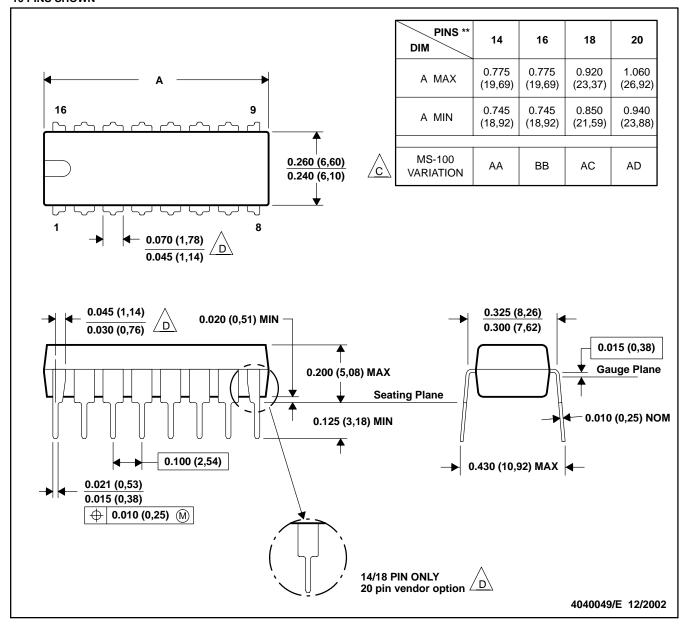
Figure 1. Load Circuit and Voltage Waveforms



#### N (R-PDIP-T\*\*)

#### **16 PINS SHOWN**

#### PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

Falls within JEDEC MS-001, except 18 and 20 pin minimum body Irngth (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

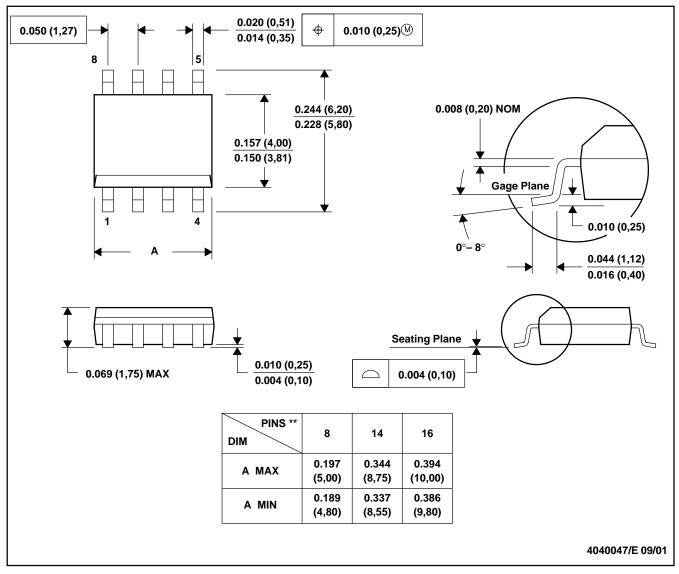


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#### D (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

#### **8 PINS SHOWN**



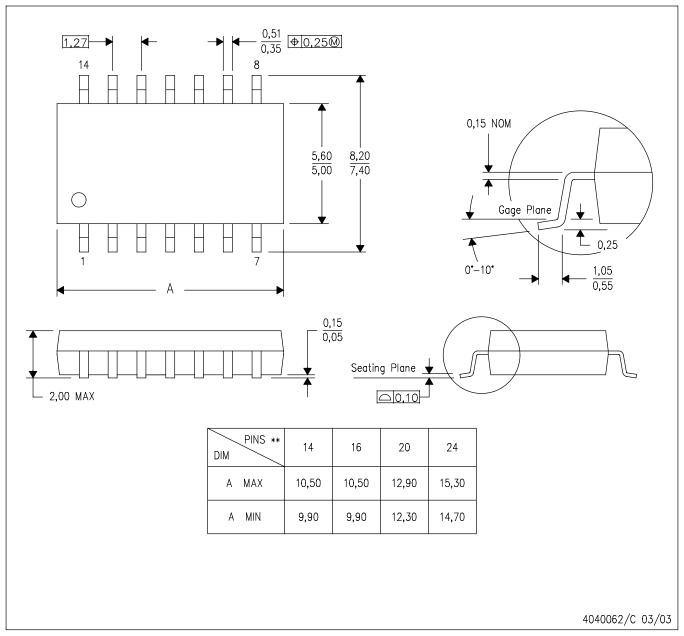
NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

14-PIN SHOWN



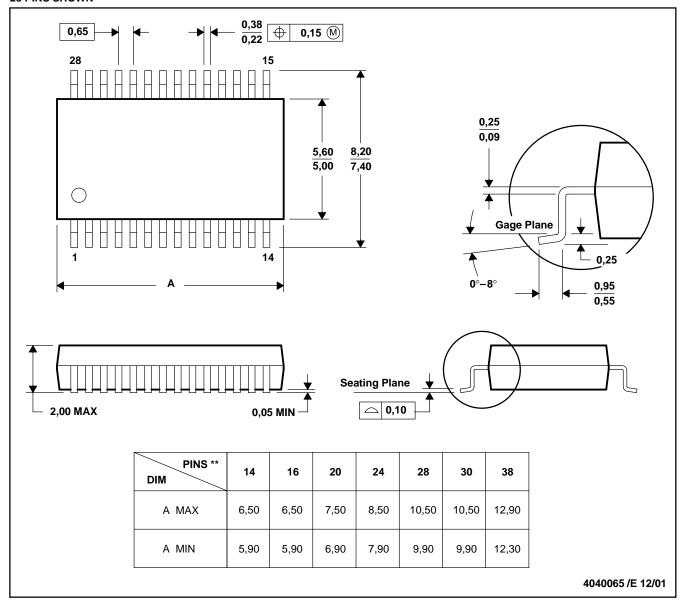
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

### DB (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

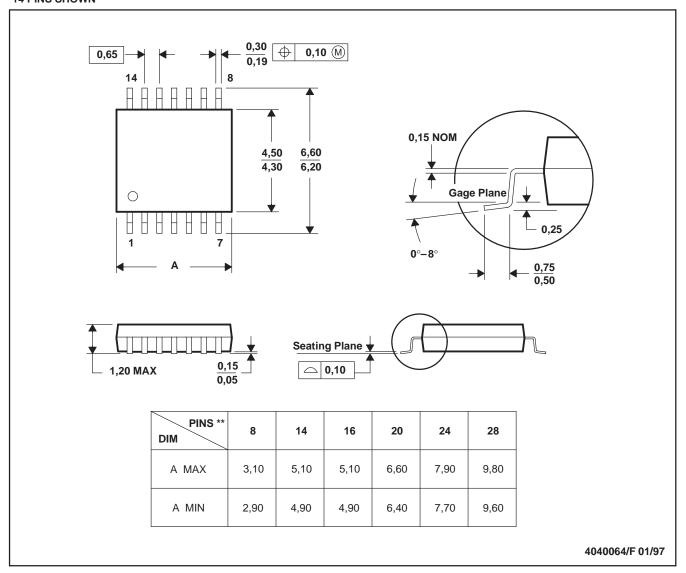
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

### PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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Mailing Address:

Texas Instruments
Post Office Box 655303
Dallas, Texas 75265

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